

Mokuzai Gakkaishi Vol. 55 (2009), No. 5 p.293-298

[PDF (939K)] [References]

Effect of Postcure Conditions on the Dynamic Mechanical Behavior of Water-Based Polymer-Isocyanate Adhesive for Wood II. Investigation of a polyvinyl alcohol solution and polymeric diphenylmethane diisocyanate model

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(Received June 16, 2008) (Accepted December 24, 2008)

Abstract: In order to understand the effect of the heat treatment on the dynamic viscoelastic behavior of water based polymer-isocyanate adhesive for wood (API adhesive), we investigated the most simplified model of the adhesive between polyvinyl alcohol (PVOH) solution and polymeric diphenylmethane diisocyanate (pMDI). Fourier transform infrared spectroscopy (FT-IR) was performed for estimating the residual isocyanate groups (NCO) and isocyanate derivatives to elucidate the reaction mechanism under the heat treatment conditions. The results are summarized as follows : (1) From DMA, a decrease of the storage modulus (E') appeared around 170° C in the sample heated below 140°C. When the treatment temperature exceeded 140°C, the samples exhibited a rapid increase in E' in the high temperature region, with a correspondingly significant chemical structure change. These results correspond with those of API adhesive. (2) The different chemical products and tendency of E' of API adhesive as compared to the PVOH-pMDI model after 2 hours of heat treatment indicates that the adding of styrene-butadiene copolymer latex (SBR) may affect progress of reaction of residual isocyanate.

Keywords: water based, isocyanate adhesive, heat treatment, dynamic mechanical analysis

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To cite this article:

Nan Ling, Naruhito Hori and Akio Takemura: Mokuzai Gakkaishi Vol. 55, No. 5, 293-298 (2009) .

doi:10.2488/jwrs.55.293 JOI JST.JSTAGE/jwrs/55.293

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